

## C1210X229D2TACAUTO

**General Information** 

**Specifications** 

Insulation Resistance

SMD Auto X8G HT150C Flex, Ceramic, 2.2 pF, +/-0.5 pF, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade, 1210, 1.5 mm



Series	SMD Auto X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Automotive Grade
Features	High Temperature, Ultra-Stable, Automotive Grade
RoHS	Yes
Termination	Flexible Termination
Marking	No
Qualifications	AEC-Q200
AEC-Q200	Yes
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1210
L	3.3mm +/-0.4mm
W	2.6mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

	Capacitance	2.2 pF
1	Measurement Condition	1 MHz 1.0Vrms
ı	Tolerance	+/-0.5 pF
mm	Voltage DC	200 VDC
	Dielectric Withstanding Voltage	500 VDC
m	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
etic Tape	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee

Time is 1000 Hours

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

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